Abstracts

Three-dimensional MMIC architecture using low thermal impedance technology

D. Hill, M. Tutt, R. Yarborough, T. Budka and Tae Kim. "Three-dimensional MMIC architecture using low thermal impedance technology." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 699-702.

A novel architecture for monolithic microwave integrated circuits (MMICs) simultaneously provides significant reduction in die area and extremely efficient heat transfer, as evidenced by 2/spl times/2 mm/sup 2/ MMICs which deliver up to 40 W CW at 1.8 GHz.

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